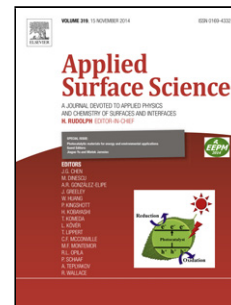


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Title: Uniform Trench Arrays with Controllable Tilted Profiles Using Metal-assisted Chemical Etching

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- **Research highlights**
 - The paper presents a facile, rapid and reliable etching technique for preparing silicon micro-trenches.
 - The fabricated trench arrays with well large-area uniformity possess the controllable tilting profiles.
 - The underlying etching kinetics and formation mechanism has been clearly revealed.

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